



Semiconductor Device Type: 3BX 008 SOIC 3.90mm(.150in) NiPdAu Plastic Gull Wing Small Outline				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials			J-STD-609A Product Marking and/or Pkg. Labeling e4				
Basic Substance	CAS Number	Contained in Sub-Component	% Total Weight	mg/part	ppm	52.54	(mg) Total	Mold Compound	% of Total Weight	70.05				
Silica, vitreous (or fused)	60676-86-0	Mold Compound	59.543	44.657	595,425		Silica, vitreous (or fused)	60676-86-0	85.00					
Epoxy Resin	Trade Secret	Mold Compound	6.094	4.571	60,944		Epoxy Resin	Trade Secret	8.70					
Phenolic Resin	Trade Secret	Mold Compound	4.203	3.152	42,030		Phenolic Resin	Trade Secret	6.00					
Carbon Black	1333-86-4	Mold Compound	0.210	0.158	2,102		Carbon Black	1333-86-4	0.30					
Copper	7440-50-8	Lead Frame	26.841	20.131	268,408		<b>Total</b>			<b>100.00</b>				
Iron	7439-89-6	Lead Frame	0.040	0.030	404		<b>20.18</b>	<b>(mg) Total</b>	<b>Lead Frame</b>	<b>% of Total Weight</b>	<b>26.90</b>			
Phosphorous	7723-14-0	Lead Frame	0.011	0.008	108		Copper	7440-50-8	99.78					
Zinc (Metal)	7440-66-6	Lead Frame	0.008	0.006	81		Iron	7439-89-6	0.15					
Silver	7440-22-4	Die Attach	0.077	0.058	770		Phosphorous	7723-14-0	0.04					
Epoxy resin	68475-94-5	Die Attach	0.020	0.015	200		Zinc (Metal)	7440-66-6	0.03					
Copper(II) oxide	1317-38-0	Die Attach	0.003	0.002	30		<b>Total</b>			<b>100.00</b>				
Silicon	7440-21-3	Chip (Die)	0.950	0.713	9,500		<b>0.08</b>	<b>(mg) Total</b>	<b>Die Attach</b>	<b>% of Total Weight</b>	<b>0.10</b>			
Copper (Cu)	7440-50-8	Wire Bond	0.488	0.366	4,875		Silver	7440-22-4	77.00					
Palladium (Pd)	7440-05-3	Wire Bond	0.012	0.009	115		Epoxy resin	68475-94-5	20.00					
Gold (Au)	7440-57-5	Wire Bond	0.001	0.001	10		Copper(II) oxide	1317-38-0	3.00					
Nickle (Ni)	7440-02-0	Plating on external leads (pins)	1.391	1.043	13,905		<b>Total</b>			<b>100.00</b>				
Palladium (Pd)	7440-05-3	Plating on external leads (pins)	0.098	0.073	975		<b>0.71</b>	<b>Total (mg)</b>	<b>Chip (Die)</b>	<b>% of Total Weight</b>	<b>0.95</b>			
Gold (Au)	7440-57-5	Plating on external leads (pins)	0.012	0.009	120		Doped Silicon	7440-21-3	100					
<b>TOTALS:</b>			<b>100.000</b>	<b>75.000</b>	<b>1,000,000</b>		<b>Total</b>			<b>100.00</b>				
<b>0.0750 g Total Mass</b>														
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)						0.38					(mg) Total	Wire Bond	% of Total Weight	0.50
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.						Copper (Cu)					7440-50-8	97.50		
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.						Palladium (Pd)					7440-05-3	2.30		
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at <a href="http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/">http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/</a>						Gold (Au)					7440-57-5	0.20		
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.						<b>Total</b>					<b>100.00</b>			
Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.						1.13				(mg) Total	Plating on external leads (pins)	% of Total Weight	1.50	
Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgement, and invoices.						Nickle (Ni)					7440-02-0	92.70		
Microchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate of Compliance for semiconductor products.						Palladium (Pd)					7440-05-3	6.50		
Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <a href="http://echa.europa.eu/web/guest/candidate-list-table">http://echa.europa.eu/web/guest/candidate-list-table</a>						Gold (Au)					7440-57-5	0.80		
						<b>Total</b>					<b>100.00</b>			
						75.00				100.00				